

GÃ¶ran N Stemme

List of Publications by Year in descending order

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226
papers

8,725
citations

41344

49
h-index

58581

82
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226
all docs

226
docs citations

226
times ranked

6724
citing authors

#	ARTICLE	IF	CITATIONS
1	Wafer-level hermetically sealed silicon photonic MEMS. <i>Photonics Research</i> , 2022, 10, A14.	7.0	18
2	3D Microvascularized Tissue Models by Laser-Based Cavitation Molding of Collagen. <i>Advanced Materials</i> , 2022, 34, e2109823.	21.0	34
3	Blood cell quantification on dry blood samples: toward patient-centric complete blood counts. <i>Bioanalysis</i> , 2022, 14, 693-701.	1.5	1
4	First Micro Swirl Nozzle for Fast Drug Delivery to the Lung. , 2021, , .		0
5	Large-area integration of two-dimensional materials and their heterostructures by wafer bonding. <i>Nature Communications</i> , 2021, 12, 917.	12.8	99
6	3D-Printing Enables Fabrication of Swirl Nozzles for Fast Aerosolization of Water-Based Drugs. <i>Journal of Microelectromechanical Systems</i> , 2021, 30, 181-183.	2.5	2
7	A microfluidic device for TEM sample preparation. <i>Lab on A Chip</i> , 2020, 20, 4186-4193.	6.0	9
8	A Self-Sealing Spray Nozzle for Aerosol Drug Delivery. <i>Journal of Microelectromechanical Systems</i> , 2020, 29, 182-189.	2.5	5
9	Vertical integration of microchips by magnetic assembly and edge wire bonding. <i>Microsystems and Nanoengineering</i> , 2020, 6, 12.	7.0	5
10	Bactericidal surfaces prepared by femtosecond laser patterning and layer-by-layer polyelectrolyte coating. <i>Journal of Colloid and Interface Science</i> , 2020, 575, 286-297.	9.4	13
11	Water in contact with the backside of a silicon substrate enables drilling of high-quality holes through the substrate using ultrashort laser pulses. <i>Optics Express</i> , 2020, 28, 1394.	3.4	6
12	Transfer printing of nanomaterials and microstructures using a wire bonder. <i>Journal of Micromechanics and Microengineering</i> , 2019, 29, 125014.	2.6	1
13	Scalable Manufacturing of Single Nanowire Devices Using Crack-Defined Shadow Mask Lithography. <i>ACS Applied Materials & Interfaces</i> , 2019, 11, 8217-8226.	8.0	21
14	An Autonomous Microfluidic Device for Generating Volume-Defined Dried Plasma Spots. <i>Analytical Chemistry</i> , 2019, 91, 7125-7130.	6.5	21
15	Wafer-Level Vacuum Sealing by Transfer Bonding of Silicon Caps for Small Footprint and Ultra-Thin MEMS Packages. <i>Journal of Microelectromechanical Systems</i> , 2019, 28, 460-471.	2.5	20
16	Evaluation of a Volumetric Dried Blood Spot Card Using a Gravimetric Method and a Bioanalytical Method with Capillary Blood from 44 Volunteers. <i>Analytical Chemistry</i> , 2019, 91, 5558-5565.	6.5	18
17	Real-time intradermal continuous glucose monitoring using a minimally invasive microneedle-based system. <i>Biomedical Microdevices</i> , 2018, 20, 101.	2.8	116
18	High-Yield Passive Plasma Filtration from Human Finger Prick Blood. <i>Analytical Chemistry</i> , 2018, 90, 13393-13399.	6.5	42

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19	Through-Glass Vias for Glass Interposers and MEMS Packaging Applications Fabricated Using Magnetic Assembly of Microscale Metal Wires. IEEE Access, 2018, 6, 44306-44317.	4.2	21
20	Scalable Manufacturing of Nanogaps. Advanced Materials, 2018, 30, e1801124.	21.0	31
21	Gas diffusion and evaporation control using EWOD actuation of ionic liquid microdroplets for gas sensing applications. Sensors and Actuators B: Chemical, 2018, 267, 647-654.	7.8	9
22	Massively parallel fabrication of crack-defined gold break junctions featuring sub-30nm gaps for molecular devices. Nature Communications, 2018, 9, 3433.	12.8	59
23	Microneedle-based system for minimally invasive continuous monitoring of glucose in the dermal interstitial fluid. , 2018, , .		4
24	(Invited) Adhesive Wafer Bonding for Heterogeneous System Integration. ECS Meeting Abstracts, 2018, , .	0.0	0
25	Wafer-Level Vacuum Packaging Enabled by Plastic Deformation and Low-Temperature Welding of Copper Sealing Rings With a Small Footprint. Journal of Microelectromechanical Systems, 2017, 26, 357-365.	2.5	15
26	Design and fabrication of crack-junctions. Microsystems and Nanoengineering, 2017, 3, 17042.	7.0	15
27	Ultra-miniaturization of a planar amperometric sensor targeting continuous intradermal glucose monitoring. Biosensors and Bioelectronics, 2017, 90, 577-583.	10.1	46
28	A sub-1/4s thermal time constant electrically driven Pt nanoheater: thermo-dynamic design and frequency characterization. Applied Physics Letters, 2016, 108, .	3.3	5
29	Flexible and Stretchable Microneedle Patches with Integrated Rigid Stainless Steel Microneedles for Transdermal Biointerfacing. PLoS ONE, 2016, 11, e0166330.	2.5	59
30	Crack-Defined Electronic Nanogaps. Advanced Materials, 2016, 28, 2178-2182.	21.0	40
31	Capacitive inertial sensing at high temperatures of up to 400 °C. Sensors and Actuators A: Physical, 2016, 238, 361-368.	4.1	3
32	A wafer-level liquid cavity integrated amperometric gas sensor with ppb-level nitric oxide gas sensitivity. Journal of Micromechanics and Microengineering, 2015, 25, 105013.	2.6	9
33	Integrating MEMS and ICs. Microsystems and Nanoengineering, 2015, 1, .	7.0	242
34	An amperometric nitric oxide sensor with fast response and ppb-level concentration detection relevant to asthma monitoring. Sensors and Actuators B: Chemical, 2015, 209, 639-644.	7.8	39
35	A low-power MEMS tunable photonic ring resonator for reconfigurable optical networks. , 2015, , .		8
36	Low-power microelectromechanically tunable silicon photonic ring resonator add-drop filter. Optics Letters, 2015, 40, 3556.	3.3	52

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37	A disposable sampling device to collect volume-measured DBS directly from a fingerprick onto DBS paper. <i>Bioanalysis</i> , 2015, 7, 2085-2094.	1.5	56
38	Stress-Minimized Packaging of Inertial Sensors by Double-Sided Bond Wire Attachment. <i>Journal of Microelectromechanical Systems</i> , 2015, 24, 781-789.	2.5	17
39	CMOS-Integrated Si/SiGe Quantum-Well Infrared Microbolometer Focal Plane Arrays Manufactured With Very Large-Scale Heterogeneous 3-D Integration. <i>IEEE Journal of Selected Topics in Quantum Electronics</i> , 2015, 21, 30-40.	2.9	35
40	Temporary Wafer Bonding and Debonding for 3D Integration Using an Electrochemically Active Polymer Adhesive. <i>ECS Journal of Solid State Science and Technology</i> , 2014, 3, P115-P121.	1.8	4
41	A MEMS-based passive air flow regulator for handheld breath diagnostics. <i>Sensors and Actuators A: Physical</i> , 2014, 215, 65-70.	4.1	3
42	A MEMS-based passive hydrocephalus shunt for body position controlled intracranial pressure regulation. <i>Biomedical Microdevices</i> , 2014, 16, 529-536.	2.8	7
43	Very large scale heterogeneous integration (VLSHI) and wafer-level vacuum packaging for infrared bolometer focal plane arrays. <i>Infrared Physics and Technology</i> , 2013, 60, 251-259.	2.9	18
44	A compact passive air flow regulator for portable breath diagnostics. , 2013, , .		1
45	Temporary wafer bonding and debonding by an electrochemically active polymer adhesive for 3D integration. , 2013, , .		2
46	Low temperature adhesive wafer bonding using OSTE(+) for heterogeneous 3D MEMS integration. , 2013, , .		0
47	Wafer-level capping and sealing of heat sensitive substances and liquids with gold gaskets. <i>Sensors and Actuators A: Physical</i> , 2013, 201, 154-163.	4.1	4
48	Pt₂/sub>O₃ dual layer atomic layer deposition coating in high aspect ratio nanopores. <i>Nanotechnology</i> , 2013, 24, 015602.	2.6	42
49	Robust actuation of silicon MEMS using SMA wires integrated at wafer-level by nickel electroplating. <i>Sensors and Actuators A: Physical</i> , 2013, 189, 108-116.	4.1	10
50	Wafer-level integration of NiTi shape memory alloy on silicon using Au–Si eutectic bonding. <i>Journal of Micromechanics and Microengineering</i> , 2013, 23, 015008.	2.6	3
51	Heterogeneous 3D integration of hidden hinge micromirror arrays consisting of two layers of monocrystalline silicon. <i>Journal of Micromechanics and Microengineering</i> , 2013, 23, 075003.	2.6	5
52	Wafer-Level Vacuum Sealing by Coining of Wire Bonded Gold Bumps. <i>Journal of Microelectromechanical Systems</i> , 2013, 22, 1347-1353.	2.5	5
53	MEMS reconfigurable millimeter-wave surface for V-band rectangular-waveguide switch. <i>International Journal of Microwave and Wireless Technologies</i> , 2013, 5, 341-349.	1.9	8
54	A low-power high-flow shape memory alloy wire gas microvalve. <i>Journal of Micromechanics and Microengineering</i> , 2012, 22, 075002.	2.6	8

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55	Wafer-level heterogeneous 3D integration for MEMS and NEMS. , 2012, , .		5
56	Hermetic integration of liquids using high-speed stud bump bonding for cavity sealing at the wafer level. Journal of Micromechanics and Microengineering, 2012, 22, 045021.	2.6	8
57	SMA Microvalves for Very Large Gas Flow Control Manufactured Using Wafer-Level Eutectic Bonding. IEEE Transactions on Industrial Electronics, 2012, 59, 4895-4906.	7.9	21
58	Layer-by-layer 3D printing of Si micro- and nanostructures by Si deposition, ion implantation and selective Si etching. , 2012, , .		1
59	Batch Transfer of Radially Expanded Die Arrays for Heterogeneous Integration Using Different Wafer Sizes. Journal of Microelectromechanical Systems, 2012, 21, 1077-1083.	2.5	7
60	Drift-Free Micromirror Arrays Made of Monocrystalline Silicon for Adaptive Optics Applications. Journal of Microelectromechanical Systems, 2012, 21, 959-970.	2.5	16
61	Very high aspect ratio through-silicon vias (TSVs) fabricated using automated magnetic assembly of nickel wires. Journal of Micromechanics and Microengineering, 2012, 22, 105001.	2.6	31
62	3D Free-Form Patterning of Silicon by Ion Implantation, Silicon Deposition, and Selective Silicon Etching. Advanced Functional Materials, 2012, 22, 4004-4008.	14.9	31
63	Electrochemically Assisted Maskless Selective Removal of Metal Layers for Three-Dimensional Micromachined SOI RF MEMS Transmission Lines and Devices. Journal of Microelectromechanical Systems, 2011, 20, 899-908.	2.5	16
64	Toward 17-µm pitch heterogeneously integrated Si/SiGe quantum well bolometer focal plane arrays. Proceedings of SPIE, 2011, , .	0.8	7
65	Wafer-level mechanical and electrical integration of SMA wires to silicon MEMS using electroplating. , 2011, , .		5
66	Wafer-Level Heterogeneous Integration for MOEMS, MEMS, and NEMS. IEEE Journal of Selected Topics in Quantum Electronics, 2011, 17, 629-644.	2.9	140
67	Power Handling Analysis of High-Power W-Band All-Silicon MEMS Phase Shifters. IEEE Transactions on Electron Devices, 2011, 58, 1548-1555.	3.0	27
68	High-performance infrared micro-bolometer arrays manufactured using very large scale heterogeneous integration. , 2011, , .		3
69	Small footprint wafer-level vacuum packaging using compressible gold sealing rings. Journal of Micromechanics and Microengineering, 2011, 21, 085011.	2.6	17
70	One-Megapixel Monocrystalline-Silicon Micromirror Array on CMOS Driving Electronics Manufactured With Very Large-Scale Heterogeneous Integration. Journal of Microelectromechanical Systems, 2011, 20, 564-572.	2.5	37
71	Fluid dynamic behavior of dispensing small droplets through a thin liquid film. Microfluidics and Nanofluidics, 2010, 9, 303-311.	2.2	6
72	Static Zero-Power-Consumption Coplanar Waveguide Embedded DC-to-RF Metal-Contact MEMS Switches in Two-Port and Three-Port Configuration. IEEE Transactions on Electron Devices, 2010, 57, 1659-1669.	3.0	26

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73	Design and Wafer-Level Fabrication of SMA Wire Microactuators on Silicon. Journal of Microelectromechanical Systems, 2010, 19, 982-991.	2.5	14
74	A packaged optical slot-waveguide ring resonator sensor array for multiplex label-free assays in labs-on-chips. Lab on A Chip, 2010, 10, 281-290.	6.0	238
75	A High-Yield Process for 3-D Large-Scale Integrated Microfluidic Networks in PDMS. Journal of Microelectromechanical Systems, 2010, 19, 1050-1057.	2.5	37
76	On-chip temperature compensation in an integrated slot-waveguide ring resonator refractive index sensor array. Optics Express, 2010, 18, 3226.	3.4	99
77	Low-temperature CMOS-compatible 3D-integration of monocrystalline-silicon based PZT RF MEMS switch actuators on rf substrates. , 2010, , .		6
78	Nanometer-scale flatness and reliability investigation of stress-compensated symmetrically-metallized monocrystalline-silicon multi-layer membranes. , 2010, , .		2
79	Deep-Reactive-Ion-Etched Wafer-Scale-Transferred All-Silicon Dielectric-Block Millimeter-Wave MEMS Phase Shifters. Journal of Microelectromechanical Systems, 2010, 19, 120-128.	2.5	12
80	CMOS-Integrable Piston-Type Micro-Mirror Array for Adaptive Optics Made of Mono-Crystalline Silicon using 3-D Integration. , 2009, , .		13
81	High-performance quantum-well silicon-germanium bolometers using IC-compatible integration for low-cost infrared imagers. , 2009, , .		13
82	Localized removal of the Au-Si eutectic bonding layer for the selective release of microstructures. Journal of Micromechanics and Microengineering, 2009, 19, 105014.	2.6	7
83	Binary-Coded 4.25-bit W-Band Monocrystalline-Silicon MEMS Multistage Dielectric-Block Phase Shifters. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 2834-2840.	4.6	43
84	Wafer bonding with nano-imprint resists as sacrificial adhesive for fabrication of silicon-on-integrated-circuit (SOIC) wafers in 3D integration of MEMS and ICs. Sensors and Actuators A: Physical, 2009, 154, 180-186.	4.1	39
85	Wafer-Scale Manufacturing of Bulk Shape-Memory-Alloy Microactuators Based on Adhesive Bonding of Titanium-Nickel Sheets to Structured Silicon Wafers. Journal of Microelectromechanical Systems, 2009, 18, 1309-1317.	2.5	26
86	Room-Temperature Sealing of Microcavities by Cold Metal Welding. Journal of Microelectromechanical Systems, 2009, 18, 1318-1325.	2.5	20
87	Membrane-sealed hollow microneedles and related administration schemes for transdermal drug delivery. Biomedical Microdevices, 2008, 10, 271-279.	2.8	82
88	Microfluidic devices for studies of primary cilium mediated cellular response to dynamic flow conditions. Biomedical Microdevices, 2008, 10, 555-560.	2.8	13
89	Performance model for uncooled infrared bolometer arrays and performance predictions of bolometers operating at atmospheric pressure. Infrared Physics and Technology, 2008, 51, 168-177.	2.9	72
90	Painless Drug Delivery Through Microneedle-Based Transdermal Patches Featuring Active Infusion. IEEE Transactions on Biomedical Engineering, 2008, 55, 1063-1071.	4.2	121

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91	Flow Sensors. , 2008, , 209-272.		11
92	An integrated QCM-based narcotics sensing microsystem. Lab on A Chip, 2008, 8, 1648.	6.0	17
93	Liquid Aspiration and Dispensing Based on an Expanding PDMS Composite. Journal of Microelectromechanical Systems, 2008, 17, 1254-1262.	2.5	10
94	Row/Column Addressing Scheme for Large Electrostatic Actuator MEMS Switch Arrays and Optimization of the Operational Reliability by Statistical Analysis. Journal of Microelectromechanical Systems, 2008, 17, 1104-1113.	2.5	11
95	A Low-Temperature Thermopneumatic Actuation Principle for Gas Bubble Microvalves. Journal of Microelectromechanical Systems, 2007, 16, 765-774.	2.5	22
96	MEMS single-chip5×5 and 20×20 double-switch arrays for telecommunication networks. , 2007, , .		3
97	Thin film crystal growth template removal: Application to stress reduction in lead zirconate titanate microstructures. Applied Physics Letters, 2007, 91, .	3.3	4
98	Robust Trimorph Bulk SMA Microactuators for Batch Manufacturing and Integration. , 2007, , .		0
99	Time-Efficient Quasi-Static Algorithm for Simulation of Complex Single-Sided Clamped Electrostatic Actuators. Journal of Microelectromechanical Systems, 2007, 16, 373-382.	2.5	6
100	Active liquid aspiration and dispensing based on an expanding PDMS composite. , 2007, , .		0
101	Mechanically tri-stable SPDT metal-contact MEMS switch embedded in 3D transmission line. , 2007, , .		3
102	MEMS for medical technology applications. , 2007, , .		1
103	A Thermally Responsive PDMS Composite and Its Microfluidic Applications. Journal of Microelectromechanical Systems, 2007, 16, 50-57.	2.5	31
104	Coplanar-waveguide embedded mechanically-bistable DC-to-RF MEMS switches. , 2007, , .		11
105	Mechanically tri-stable SPDT metal-contact MEMS switch embedded in 3D transmission line. , 2007, , .		4
106	A method for tapered deep reactive ion etching using a modified Bosch process. Journal of Micromechanics and Microengineering, 2007, 17, 1087-1092.	2.6	53
107	Uncooled infrared bolometer arrays operating in a low to medium vacuum atmosphere: performance model and tradeoffs. , 2007, , .		27
108	Low-cost far infrared bolometer camera for automotive use. , 2007, , .		22

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109	Penetration-Enhanced Ultrasharp Microneedles and Prediction on Skin Interaction for Efficient Transdermal Drug Delivery. <i>Journal of Microelectromechanical Systems</i> , 2007, 16, 1429-1440.	2.5	153
110	Smart Individual Switch Addressing of 5 \times 5 and 20 \times 20 MEMS Double-Switch Arrays. , 2007, , .		5
111	Novel room-temperature wafer-to-wafer attachment and sealing of cavities using cold metal welding. , 2007, , .		2
112	Thermosetting nano-imprint resists: novel materials for adhesive wafer bonding. , 2007, , .		10
113	Wafer-Level Process for Single-Use Buckling-Film Microliter-Range Pumps. <i>Journal of Microelectromechanical Systems</i> , 2007, 16, 795-801.	2.5	10
114	Tapered Deep Reactive Ion Etching: Method and Characterization. , 2007, , .		6
115	A miniaturised integrated QCM-based electronic nose microsystem. , 2007, , .		2
116	The fabrication of microfluidic structures by means of full-wafer adhesive bonding using a poly(dimethylsiloxane) catalyst. <i>Journal of Micromechanics and Microengineering</i> , 2007, 17, 1710-1714.	2.6	63
117	Off-line integration of CE and MALDI-MS using a closedâ€“openâ€“closed microchannel system. <i>Electrophoresis</i> , 2007, 28, 2458-2465.	2.4	19
118	A microfluidic device for parallel \times cell cultures in asymmetric environments. <i>Electrophoresis</i> , 2007, 28, 4705-4712.	2.4	36
119	Novel Microneedle Patches for Active Insulin Delivery are Efficient in Maintaining Glycaemic Control: An Initial Comparison with Subcutaneous Administration. <i>Pharmaceutical Research</i> , 2007, 24, 1381-1388.	3.5	103
120	A disposable lab-on-a-chip platform with embedded fluid actuators for active nanoliter liquid handling. <i>Biomedical Microdevices</i> , 2007, 9, 61-67.	2.8	33
121	Mechanically tri-stable, true single-pole-double-throw (SPDT) switches. <i>Journal of Micromechanics and Microengineering</i> , 2006, 16, 2251-2258.	2.6	47
122	Active Opening Force and Passive Contact Force Electrostatic Switches for Soft Metal Contact Materials. <i>Journal of Microelectromechanical Systems</i> , 2006, 15, 1235-1242.	2.5	39
123	A micromachined interface for airborne sample-to-liquid transfer and its application in a biosensor system. <i>Lab on A Chip</i> , 2006, 6, 1504-1509.	6.0	31
124	Out-of-Plane Knife-Gate Microvalves for Controlling Large Gas Flows. <i>Journal of Microelectromechanical Systems</i> , 2006, 15, 1281-1288.	2.5	7
125	MEMS single-chip microswitch array for re-configuration of telecommunication networks. , 2006, , .		3
126	Rapid Melting Curve Analysis on Monolayered Beads for High-Throughput Genotyping of Single-Nucleotide Polymorphisms. <i>Analytical Chemistry</i> , 2006, 78, 2220-2225.	6.5	35

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127	A compact, low-cost microliter-range liquid dispenser based on expandable microspheres. Journal of Micromechanics and Microengineering, 2006, 16, 2740-2746.	2.6	15
128	Fulfilling the pedestrian protection directive using a long-wavelength infrared camera designed to meet both performance and cost targets. , 2006, 6198, 74.		11
129	Adhesive copper films for an air-breathing polymer electrolyte fuel cell. Journal of Power Sources, 2005, 144, 113-121.	7.8	28
130	A concept for miniaturized 3-D cell culture using an extracellular matrix gel. Electrophoresis, 2005, 26, 4751-4758.	2.4	34
131	BCB contact printing for patterned adhesive full-wafer bonded 0-level packages. Journal of Microelectromechanical Systems, 2005, 14, 419-425.	2.5	50
132	Hybrid-mounted micromachined aluminum hotwires for wall shear-stress measurements. Journal of Microelectromechanical Systems, 2005, 14, 254-260.	2.5	9
133	Behaviour and design considerations for continuous flow closed-open-closed liquid microchannels. Lab on A Chip, 2005, 5, 682.	6.0	40
134	A seat microvalve nozzle for optimal gas-flow capacity at large-controlled pressure. Journal of Microelectromechanical Systems, 2005, 14, 200-206.	2.5	13
135	Pyrosequencing in a Microfluidic Flow-Through Device. Analytical Chemistry, 2005, 77, 7505-7511.	6.5	22
136	Characterization of transfer-bonded silicon bolometer arrays. , 2004, , .		21
137	Low-Voltage High-Isolation DC-to-RF MEMS Switch Based on an S-shaped Film Actuator. IEEE Transactions on Electron Devices, 2004, 51, 149-155.	3.0	31
138	A liquid-triggered liquid microvalve for on-chip flow control. Sensors and Actuators B: Chemical, 2004, 100, 463-468.	7.8	63
139	Genotyping by dynamic heating of monolayered beads on a microheated surface. Electrophoresis, 2004, 25, 3712-3719.	2.4	14
140	Sealing of adhesive bonded devices on wafer level. Sensors and Actuators A: Physical, 2004, 110, 407-412.	4.1	53
141	Design and Fabrication Aspects of an S-Shaped Film Actuator Based DC to RF MEMS Switch. Journal of Microelectromechanical Systems, 2004, 13, 421-428.	2.5	36
142	A fast passive and planar liquid sample micromixer. Lab on A Chip, 2004, 4, 214-219.	6.0	70
143	Characteristics of a hot-wire microsensor for time-dependent wall shear stress measurements. Experiments in Fluids, 2003, 35, 240-251.	2.4	24
144	A diode-based two-wire solution for temperature-compensated piezoresistive pressure sensors. IEEE Transactions on Electron Devices, 2003, 50, 503-509.	3.0	15

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145	Single-nucleotide polymorphism analysis by allele-specific extension of fluorescently labeled nucleotides in a microfluidic flow-through device. <i>Electrophoresis</i> , 2003, 24, 158-161.	2.4	38
146	A lift force sensor with integrated hot-chips for wide range flow measurements. <i>Sensors and Actuators A: Physical</i> , 2003, 109, 120-130.	4.1	28
147	Single nucleotide polymorphism analysis by allele-specific primer extension with real-time bioluminescence detection in a microfluidic device. <i>Journal of Chromatography A</i> , 2003, 1014, 37-45.	3.7	24
148	Selective wafer-level adhesive bonding with benzocyclobutene for fabrication of cavities. <i>Sensors and Actuators A: Physical</i> , 2003, 105, 297-304.	4.1	96
149	A method to maintain wafer alignment precision during adhesive wafer bonding. <i>Sensors and Actuators A: Physical</i> , 2003, 107, 273-278.	4.1	43
150	Characterization of micromachined hollow tips for two-dimensional nanoelectrospray mass spectrometry. <i>Rapid Communications in Mass Spectrometry</i> , 2003, 17, 337-341.	1.5	41
151	Arrays of monocrystalline silicon micromirrors fabricated using CMOS compatible transfer bonding. <i>Journal of Microelectromechanical Systems</i> , 2003, 12, 465-469.	2.5	46
152	A static turbine flow meter with a micromachined silicon torque sensor. <i>Journal of Microelectromechanical Systems</i> , 2003, 12, 937-946.	2.5	30
153	A new edge-detected lift force flow sensor. <i>Journal of Microelectromechanical Systems</i> , 2003, 12, 344-354.	2.5	33
154	Side-opened out-of-plane microneedles for microfluidic transdermal liquid transfer. <i>Journal of Microelectromechanical Systems</i> , 2003, 12, 296-301.	2.5	192
155	Handling of beads in microfluidic devices for biotech applications. , 2003, , 187-204.		1
156	Development of micromachined hollow tips for protein analysis based on nanoelectrospray ionization mass spectrometry. <i>Journal of Micromechanics and Microengineering</i> , 2002, 12, 682-687.	2.6	55
157	Self-assembled and self-sorted array of chemically active beads for analytical and biochemical screening. <i>Talanta</i> , 2002, 56, 301-308.	5.5	31
158	Characterization of micromachined spiked biopotential electrodes. <i>IEEE Transactions on Biomedical Engineering</i> , 2002, 49, 597-604.	4.2	128
159	Immobilized oxazoline-containing Ligands in asymmetric catalysisâ€”a review. <i>Bioorganic and Medicinal Chemistry Letters</i> , 2002, 12, 1857-1861.	2.2	35
160	Micromachined barbed spikes for mechanical chip attachment. <i>Sensors and Actuators A: Physical</i> , 2002, 95, 94-99.	4.1	29
161	A free-hanging strain-gauge for ultraminiaturized pressure sensors. <i>Sensors and Actuators A: Physical</i> , 2002, 97-98, 75-82.	4.1	21
162	A high-stroke, high-pressure electrostatic actuator for valve applications. <i>Sensors and Actuators A: Physical</i> , 2002, 100, 264-271.	4.1	64

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163	A micropneumatic-to-vibration energy converter concept. Sensors and Actuators A: Physical, 2002, 100, 77-83.	4.1	3
164	A temperature compensated dual beam pressure sensor. Sensors and Actuators A: Physical, 2002, 100, 46-53.	4.1	19
165	Expandable microspheresâ€™ surface immobilization techniques. Sensors and Actuators B: Chemical, 2002, 84, 290-295.	7.8	18
166	Expandable microspheres for the handling of liquids. Lab on A Chip, 2002, 2, 117.	6.0	66
167	Detection of Single Nucleotide Incorporation Using Pyrosequencing in a Microfluidic Device. , 2002, , 308-310.		2
168	SNP Analysis by Allele-Specific Extension of Fluorescently Labeled Nucleotides in a Microfluidic Flow-Through Device. , 2002, , 218-220.		1
169	Beads in Biochemical Microfluidics. , 2002, , 605-607.		3
170	Micromachined electrodes for biopotential measurements. Journal of Microelectromechanical Systems, 2001, 10, 10-16.	2.5	192
171	Low-temperature wafer-level transfer bonding. Journal of Microelectromechanical Systems, 2001, 10, 525-531.	2.5	56
172	Low-temperature full wafer adhesive bonding. Journal of Micromechanics and Microengineering, 2001, 11, 100-107.	2.6	219
173	Highly sensitive triaxial silicon accelerometer with integrated PZT thin film detectors. Sensors and Actuators A: Physical, 2001, 92, 156-160.	4.1	70
174	Low temperature full wafer adhesive bonding of structured wafers. Sensors and Actuators A: Physical, 2001, 92, 235-241.	4.1	75
175	A valve-less diffuser micropump for microfluidic analytical systems. Sensors and Actuators B: Chemical, 2001, 72, 259-265.	7.8	193
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